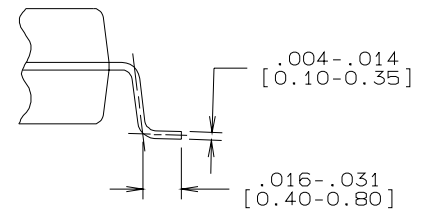
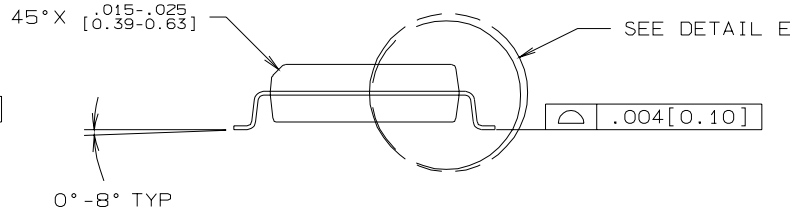
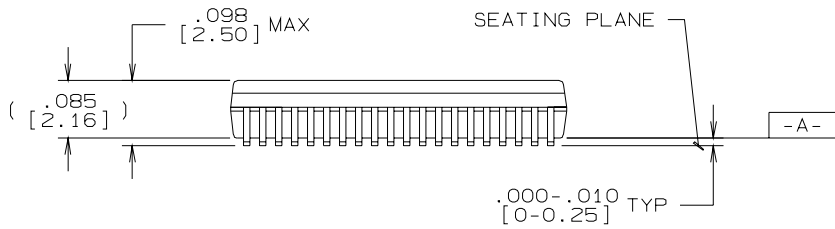


⊕ .004 [0.10] M A C S B

REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	08419	04/01/91	DEG/



DETAIL E TYP



NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH:  
200 MICROINCHES/5.08 MICROMETERS MINIMUM LEAD/TIN  
(SOLDER) ON COPPER.

(2) DIMENSION DOES NOT INCLUDE MOLD FLASH.

CONTROLLING DIMENSION: MILLIMETER

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION 2900 Semiconductor Drive, Santa Clara, CA 95052-8090			
DRAWN D.E. GRADY	04/01/91	MOLDED PACKAGE, SSOP, EIAJ TYPE III, 40 LEAD			
DFTG. CHK.					
ENGR. CHK.					
APPROVAL		SCALE N/A	SIZE B	DRAWING NUMBER MKT-MS40A	REV A
PROJECTION INCH [MM]		DO NOT SCALE DRAWING		SHEET 1 OF 1	